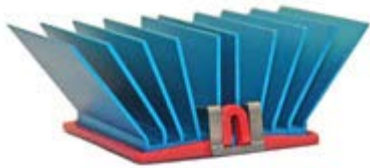


BGA Heat Sink - High Performance maxiFLOW/superGRIP



ATS Part#:	ATS-X50150B-C1-R0
Description:	15.00 x 15.00 x 7.50 mm BGA Heat Sink - High Performance maxiFLOW/superGRIP
Heat Sink Type:	maxiFLOW
Heat Sink Attachment:	superGRIP
Equivalent Part Number:	N/A

*Image above is for illustration purpose only.

Features & Benefits

- Designed for 15 x 15 mm components.
- Requires minimal space around the component's perimeter; ideal for densely populated PCBs
- Allows the heat sink to be detached and reattached without damaging the component or the PCB, an important feature in the event a PCB may need to be reworked
- Strong, uniform attachment force helps achieve maximum performance from phase-changing TIMs
- Eliminates the need to drill mounting holes in the PCB

Thermal Performance

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	19.7 °C/W	15.9 °C/W	13.8 °C/W	12.3 °C/W	11.2 °C/W	10.4 °C/W	9.7 °C/W
	Ducted Flow	14.6	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail

Schematic Image	Dimension A	Dimension B	Dimension C	Dimension D	TIM	Finish
	15.00 mm	15.00 mm	7.50 mm	27.9 mm	T766	BLUE-ANODIZED
Notes: • Dimension A and B refer to component size. • Dimension C is the heat sink height from the bottom of the base to the top of the fin field. • Thermal performance data are provided for reference only. Actual performance may vary by application. • ATS reserves the right to update or change its products without notice to improve the design or performance. • ATS certifies that this heat sink assembly is RoHS-6 and REACH compliant. • Contact ATS to learn about custom options available.						

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